PCN Number:		20160201003				PCN Date:		2/08/2016	
Title: Datasheet for		- BQ24392-Q1							
Customer Contact:		PCN Manager	PCN Manager D			ept:	Quality Services		
Change	e Type:								
	sembly Site		Design				Wafer Bump Site		
	sembly Process		🛛 Data Sheet				Wafer Bump Material		
Assembly Materials							Vafer Bump Process		
Mechanical Specific							Fab Site		
Packing/Shipping/		Labeling		Test Process		-		Materials	
<u> </u>						Wafe	- Fab	Process	
Notification Details									
Description of Change:									
Texas Instruments Incorporated is announcing an information only notification.									
The product datasheet(s) is updated as seen in the change revision history below:									
TEXAS INSTRUMENTS									
BQ24392-Q1									
SLIS160C – AUGUST 2014–REVISED JANUARY 2016 www.ti.com									
Changes from Revision B (January 2015) to Revision C Page							Page		
Changed diode direction from left facing to right facing in Application Schematic									
Device Family			Change From:			Change To:			
BQ24392-Q1			SLIS160B			SLIS160C			
These changes may be reviewed at the datasheet links provided.									
http://www.ti.com/product/bg24392-g1									
Reason for Change:									
To accurately illustrate Application Schematic									
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):									
No anticipated impact. This is a specification change announcement only. There are no changes									
to the actual device.									
Changes to product identification resulting from this PCN:									
None.									
Product Affected:									
BQ2439	2QRSERQ1								

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com